



HALF BRIDGE GATE DRIVER IN SO-14

Description

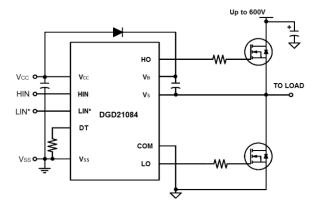
The DGD21084 is a high voltage / high speed gate driver capable of driving N-Channel MOSFETs and IGBTs in a half bridge configuration. High voltage processing techniques enable the DGD21084's high-side to switch to 600V in a bootstrap operation.

The DGD21084 logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) for easy interfacing with controlling devices. The driver outputs feature high pulse current buffers designed for minimum driver cross conduction. Programmable dead time, by an external resistor, provides more system level flexibility.

The DGD21084 is offered in SO-14 (Type TH) package, the operating temperature extends from -40°C to +125°C.

Applications

- DC-DC Converters
- DC-AC Inverters
- AC-DC Power Supplies
- Motor Controls
- Class D Power Amplifiers



Typical Configuration

Features

- Floating High-side Driver in Bootstrap Operation to 600V
- Drives Two N-Channel MOSFETs or IGBTs in a Half Bridge Configuation
- Outputs Tolerant to Negative Transients
- Programmable Dead Time to Protect MOSFETs
- Wide Logic and Low-side Gate Driver Supply Voltage: 10V to 20V
- Wide Logic Supply Voltage Offset Voltage: -5V to 5V
- Logic Inputs (HIN and LIN*) 3.3V Capability
- Schmitt Triggered Logic Inputs with Internal Pull Down
- Undervoltage Lockout For High and Low Side Drivers
- Extended Temperature Range: -40°C to +125°C
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
 - Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: SO-14 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 <a>(3)
- Weight: 0.142 grams (Approximate)



SO-14 (Type TH) Top View

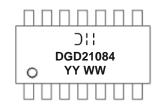
Ordering Information (Note 4)

Product	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DGD21084S14-13	DGD21084	13	16	2,500

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

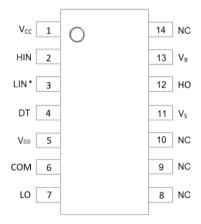
Marking Information



Oll = Manufacturer's marking DGD21084 = Product Type Marking Code YY = Year (ex: 16 = 2016) WW = Week (01 to 53)



Pin Diagrams

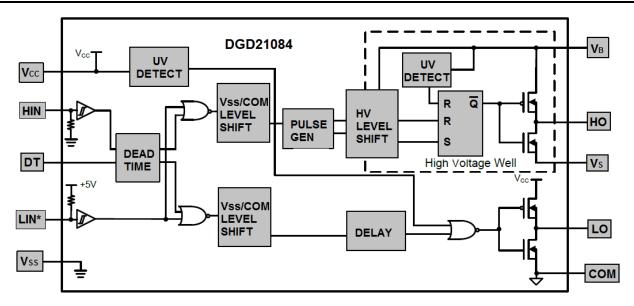


Top View SO-14 (Type TH)

Pin Descriptions

Pin Number	Pin Name	Function
1	Vcc	Low-side and logic fixed supply
2	HIN	Logic input for high-side gate driver output, in phase with HO (Referenced to V _{SS})
3	LIN*	Logic input for low-side gate driver output, out of phase with LO (Referenced to V _{SS})
4	DT	Programmable dead time lead (Referenced to V _{SS})
5	V_{SS}	Logic ground
6	COM	Low-side return
7	LO	Low-side gate drive output
8,9,10, 14	NC	No Connect (No Internal Connection)
11	Vs	High-side floating supply return
12	НО	High-side gate drive output
13	V_{B}	High-side floating supply

Functional Block Diagram





Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-side Floating Supply Voltage	V _B	-0.3 to +624	V
High-side Floating Supply Offset Voltage	Vs	V _B -24 to V _B +0.3	V
High-side Floating Output Voltage	V _{HO}	V _S -0.3 to V _B +0.3	V
Offset Supply Voltage Transient	dV _S / dt	50	V/ns
Programmable Dead Time Pin Voltage	V_{DT}	V _{SS} -0.3 to V _B +0.3	V
Low-side Fixed Supply Voltage	Vcc	-0.3 to +24	V
Low-side Output Voltage	V _{LO}	-0.3 to V _{CC} +0.3	V
Logic Supply Voltage	V _{CC}	-0.3 to V _{SS} +24	V
Logic Supply Offset Voltage	V _{SS}	V _{CC} -25 to V _{CC} +0.3	V
Logic Input Voltage (HIN and LIN*)	V _{IN}	V _{SS} -0.3 to V _{CC} +0.3	V

Thermal Characteristics ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	P_{D}	1.0	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	120	°C/W
Operating Temperature	TJ	+150	
Lead Temperature (Soldering, 10s)	T_L	+300	°C
Storage Temperature Range	T _{STG}	-55 to +150	

Note:

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High-side Floating Supply Absolute Voltage	V_{B}	V _S + 10	V _S + 20	V
High-side Floating Supply Offset Voltage	Vs	(Note 6)	600	V
High-side Floating Output Voltage	V_{HO}	Vs	V_{B}	V
Low-side Fixed Supply Voltage	V _{CC}	10	20	V
Low-side Output Voltage	V_{LO}	0	V _{CC}	V
Logic Input Voltage (HIN & LIN*)	V _{IN}	V _{SS}	Vcc	V
Programmable Dead Time Pin Voltage	V_{DT}	V _{SS}	V _{CC}	V
Logic Ground	V _{SS}	-5	5	V
Ambient Temperature	T _A	-40	+125	°C

Note:

^{5.} When mounted on a standard JEDEC 2-layer FR-4 board.

^{6.} Logic operation for $V_S = -5V$ to +600V. Logic state held for VS of -5V to -VBS.



$\hline \textbf{DC Electrical Characteristics} \ (V_{BIAS} \ (V_{CC}, V_{BS}) = 15 \text{V}, \ V_{SS} = \text{COM}, \ @T_{A} = +25 ^{\circ}\text{C}, \ unless otherwise specified.}) \ (\text{Note 7})$

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Logic "1" Input Voltage	V_{IH}	2.5	-	-	V	$V_{CC} = 10V$ to $20V$
Logic "0" Input Voltage	V_{IL}	_	-	0.6	V	$V_{CC} = 10V$ to $20V$
High-level Output Voltage, V _{BIAS} - V _O	V _{OH}	-	0.02	0.2	V	$I_O = 2mA$
Low-level Output Voltage, VO	V_{OL}	_	0.02	0.1	V	$I_O = 2mA$
Offset Supply Leakage Current	I _{LK}	-	-	50	μΑ	$V_B = V_S = 600V$
Quiescent V _{BS} Supply Current	I _{BSQ}	20	75	130	μΑ	V _{IN} = 0V or 5V
Quiescent V _{CC} Supply Current	I _{CCQ}	0.4	1.0	1.6	mA	$V_{IN} = 0V \text{ or } 5V, R_{DT} = 0\Omega$
Logic "1" Input Bias Current	I _{IN+}	_	5	20	μΑ	HIN = 5V, LIN* = 0V
Logic "0" Input Bias Current	I _{IN-}	_	_	5	μΑ	HIN = 0V, LIN* = 5V
V _{BS} Supply Under-voltage Positive Going Threshold	V _{BSUV+}	8.0	8.9	9.8	V	_
V _{BS} Supply Under-voltage Negative Going Threshold	V _{BSUV} -	7.4	8.2	9.0	V	_
V _{CC} Supply Under-voltage Positive Going Threshold	V _{CCUV+}	8.0	8.9	9.8	V	_
V _{CC} Supply Under-voltage Negative Going Threshold	V _{CCUV} -	7.4	8.2	9.0	V	_
Hysteresis	V _{CCUV+}	0.3	0.7	_	V	_
,	V _{BSUV+}					_
Output High Short Circuit Pulsed Current	I _{O+}	120	200	_	mA	$V_O = 0V$, $PW \le 10\mu s$
Output Low Short Circuit Pulsed Current	I _{O-}	250	600	_	mA	$V_0 = 15V$, PW $\leq 10\mu s$

Note: 7. The V_{IN} and I_{IN} parameters are referenced to V_{SS} and are applicable to the two logic input pins: HIN and LIN*. The V_O and I_O parameters are referenced to COM and are applicable to the respective output pins: HO and LO.

AC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, V_{SS} = COM, C_L = 1000pF, @T_A = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Turn-on Propagation Delay	t _{ON}	_	220	300	ns	$V_S = 0V$
Turn-off Propagation Delay	t _{OFF}	_	200	280	ns	$V_S = 0V \text{ or } 600V$
Delay Matching, ton - toff	t _{DMON}	_	0	30	ns	_
Turn-on Rise Time	t _R	_	100	220	ns	$V_S = 0V$
Turn-off Fall Time	t _F	_	35	80	ns	$V_S = 0V$
Doodtime: tt	t _{DT}	400	540	680	ns	$R_{DT} = 0\Omega$
Deadtime: t _{DT LO-HO} & t _{DT HO-LO}		4	5	6	us	$R_{DT} = 200 \text{K}\Omega$ (Note 8)
Deadtine Matchine	t _{MDT}	_	0	60	ns	$R_{DT} = 0\Omega$
Deadtime Matching = t _{DT} LO-HO - t _{DT} HO-LO		_	0	600	ns	$R_{DT} = 200 K\Omega$

Note: 8. Guaranted by design, not tested in production.



Timing Waveforms

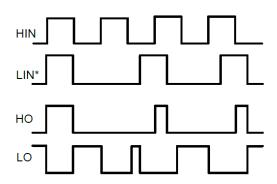


Figure 1. Input / Output Timing Diagram

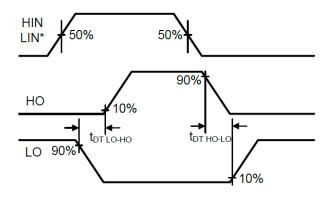
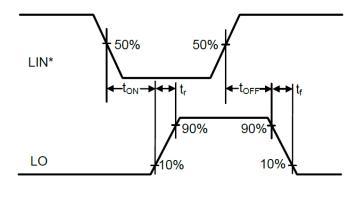


Figure 2. Deadtime Waveform Definitions



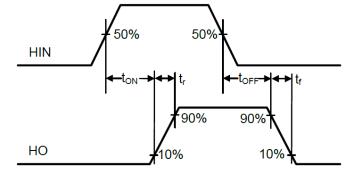


Figure 3. Switching Time Waveform Definitions



Typical Performance Characteristics (@TA = +25°C, unless otherwise specified.)

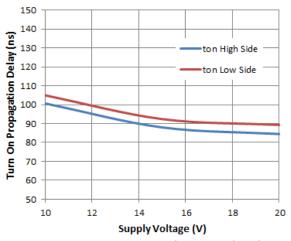


Figure 4. Turn-on Propagation Delay vs. Supply Voltage

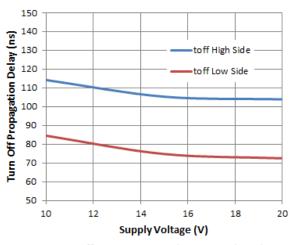


Figure 6. Turn-off Propagation Delay vs. Supply Voltage

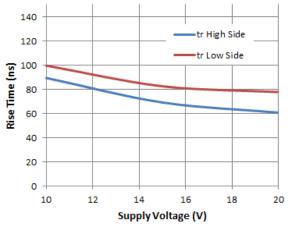


Figure 8. Rise Time vs. Supply Voltage

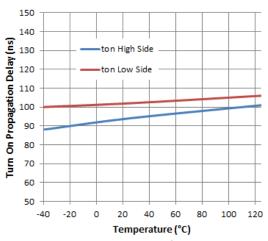


Figure 5. Turn-on Propagation Delay vs. Temperature

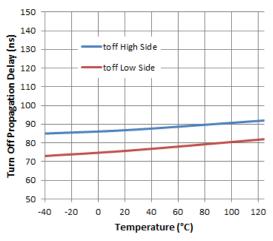


Figure 7. Turn-off Propagation Delay vs. Temperature

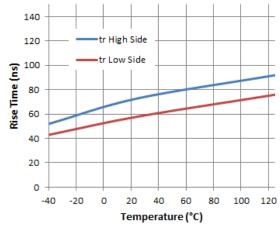


Figure 9. Rise Time vs. Temperature



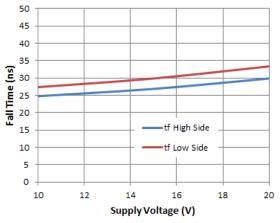


Figure 10. Fall Time vs. Supply Voltage

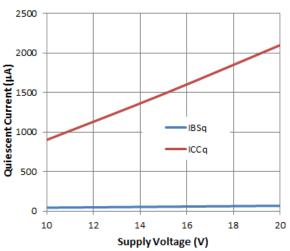


Figure 12. Quiescent Current vs. Supply Voltage

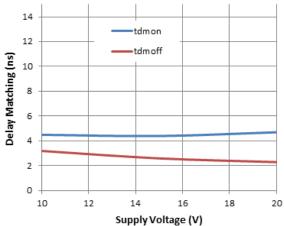


Figure 14. Delay Matching vs. Supply Voltage

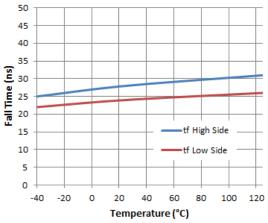


Figure 11. Fall Time vs. Temperature

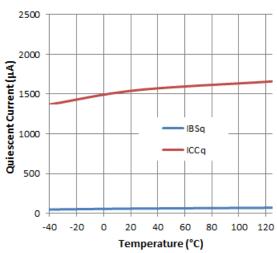


Figure 13. Quiescent Current vs. Temperature

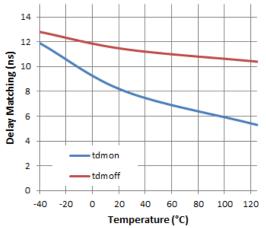


Figure 15. Delay Matching vs. Temperature



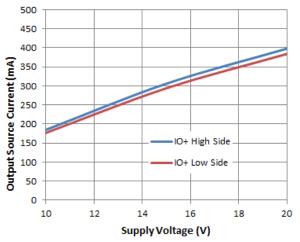


Figure 16. Output Source Current vs. Supply Voltage

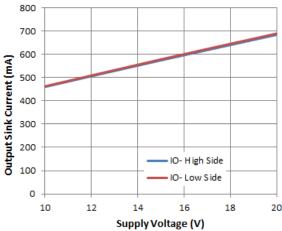


Figure 18. Output Sink Current vs. Supply Voltage

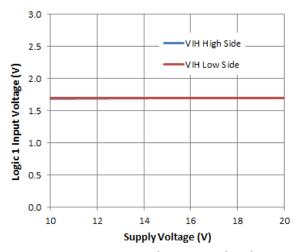


Figure 20. Logic 1 Input Voltage vs. Supply Voltage

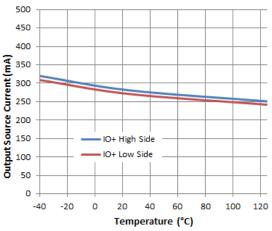


Figure 17. Output Source Current vs. Temperature

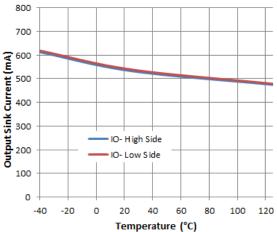


Figure 19. Output Sink Current vs. Temperature

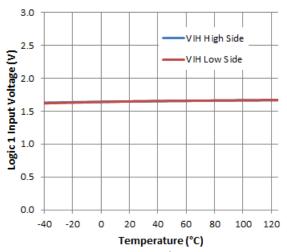


Figure 21. Logic 1 Input Voltage vs. Temperature



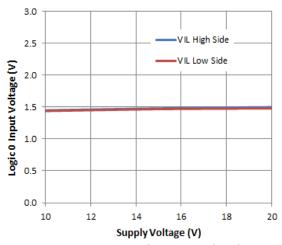


Figure 22. Logic O Input Voltage vs. Supply Voltage

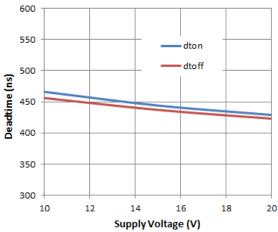


Figure 24. Deadtime vs. Supply Voltage

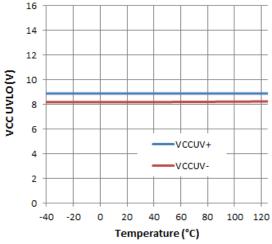


Figure 26. VCC UVLO vs. Temperature

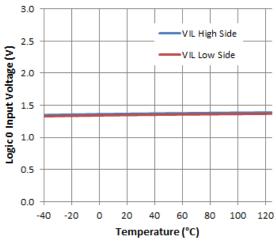


Figure 23. Logic 0 Input Voltage vs. Temperature

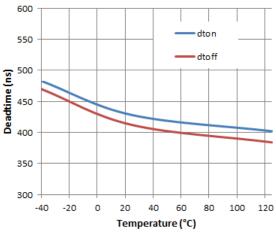


Figure 25. Deadtime vs. Temperature

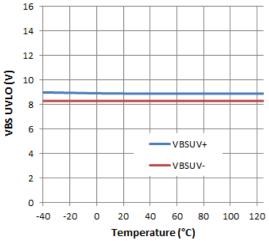


Figure 27. VBS UVLO vs. Temperature



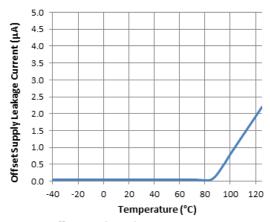


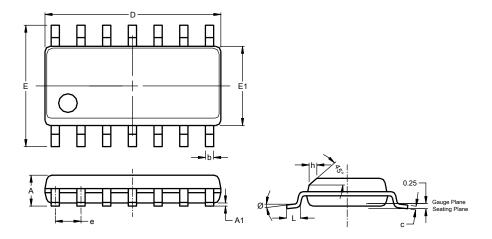
Figure 28. Offset Supply Leakage Current vs. Temperature



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-14 (Type TH)

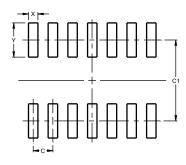


SO-14 (Type TH)					
Dim	Min	Max	Тур		
Α	1.55	1.73			
A1	0.10	0.25			
b	0.35	0.51			
С	0.190	0.248			
D	8.56	8.74	8.61		
Е	5.84	6.20	6.00		
E1	3.81	3.99	3.94		
е			1.27		
h			0.33		
L	0.41	0.89			
Ø	0°	8°			
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-14 (Type TH)



Dimensions	Value (in mm)
С	1.27
C1	5.20
Х	0.60
Υ	2 20

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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